

## Reliability and Test Condition

Item	Performance	Test Condition
<b>Electrical Performance Test</b>		
Inductance	Refer to standard electrical characteristics list	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter
DCR		CH16502,Agilent33420A Micro-Ohm Meter
Saturation Current (Isat)	Approximately $\Delta L30\%$ .	Saturation DC Current (Isat) will cause L0 to drop $\Delta L(\%)$
Heat Rated Current (Irms)	Approximately $\Delta T40^{\circ}\text{C}$	Heat Rated Current (Irms) will cause the coil temperature rise $\Delta T(^{\circ}\text{C})$ without core loss. 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Operating Temperature	-40 $^{\circ}\text{C}$ ~+125 $^{\circ}\text{C}$ (Including self - temperature rise)	
Storage Temperature	1.-10~+40 $^{\circ}\text{C}$ ,50~60% RH (Product without taping) 2.-40~+125 $^{\circ}\text{C}$ (on board)	
<b>Reliability Test</b>		
Life Test	Appearance : No damage Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times. ( IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature : 125 $\pm 2^{\circ}\text{C}$ (Inductor) Applied current : rated current Duration : 1000 $\pm 12$ hrs Measured at room temperature after placing for 24 $\pm 2$ hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times. ( IPC/JEDEC J-STD-020D Classification Reflow Profiles) Humidity : 85 $\pm 2\%$ R.H Temperature : 85 $^{\circ}\text{C} \pm 2^{\circ}\text{C}$ Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24 $\pm 2$ hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times. ( IPC/JEDEC J-STD-020D Classification Reflow Profiles) 1. Baked at50 $^{\circ}\text{C}$ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65 $\pm 2^{\circ}\text{C}$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25 $^{\circ}\text{C}$ in 2.5hrs. 3. Raise temperature to 65 $\pm 2^{\circ}\text{C}$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25 $^{\circ}\text{C}$ in 2.5hrs, keep at 25 $^{\circ}\text{C}$ for 2 hrs then keep at -10 $^{\circ}\text{C}$ for 3 hrs 4. Keep at 25 $^{\circ}\text{C}$ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times. ( IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1 : -40 $\pm 2^{\circ}\text{C}$ 30 $\pm 5$ min Step2 : 25 $\pm 2^{\circ}\text{C}$ $\leq 0.5$ min Step3 : 125 $\pm 2^{\circ}\text{C}$ 30 $\pm 5$ min Number of cycles : 500 Measured at room temperature after placing for 24 $\pm 2$ hrs
Vibration		Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:1.52mm $\pm 10\%$ Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)

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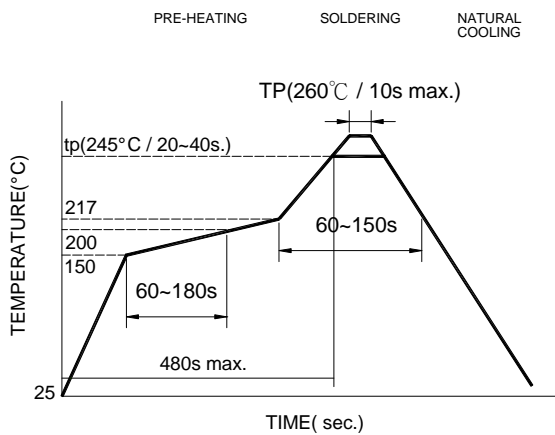
Item	Performance	Test Condition																		
<b>Reliability Test</b>																				
Shock	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value RDC : within ±15% of initial value and shall not exceed the specification value	<table border="1"> <thead> <tr> <th rowspan="2">Type</th> <th>Peak value</th> <th>Normal</th> <th rowspan="2">Wave form</th> <th>Velocity</th> </tr> <tr> <th>(g's)</th> <th>duration (D) (ms)</th> <th>change (Vi)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak value	Normal	Wave form	Velocity	(g's)	duration (D) (ms)	change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
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Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805:40x100x1.2mm <0805:40x100x0.8mm Bending depth: >=0805:1.2mm <0805:0.8mm duration of 10 sec.																		
Soderability	More than 95% of the terminal electrode should be covered with solder	Preheat: 150°C,60sec Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C Flux for lead free: Rosin. 9.5% Dip time: 4±1sec Depth: completely cover the termination																		
Resistance to Soldering Heat		Number of heat cycles: 1 <table border="1"> <thead> <tr> <th>Temperature (°C)</th> <th>Time (s)</th> <th>Temperature ramp/immersion and emersion rate</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> </tr> </tbody> </table>	Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s												
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Terminal Strength	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning:Run through IR reflow for 2 times ( IPC/JEDEC J-STD-020D Classification Reflow Profiles) With the component mounted on a PCB with the device to be tested, apply a force (>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.																		

Note : When there are questions concerning measurement result measurement shall be made after 48 ± 2 hours Of recovery under the standard condition.

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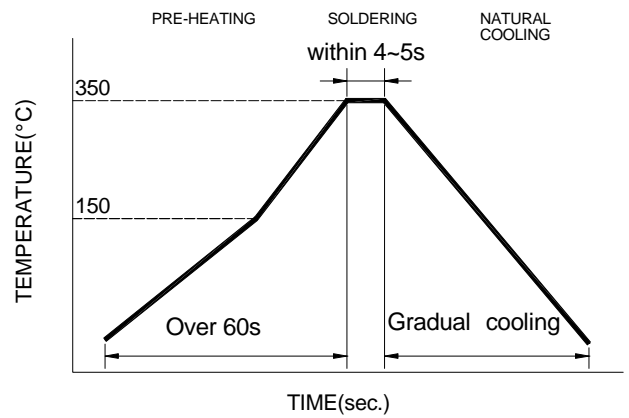
Item	Performance	Test Condition
<b>Reliability Test</b>		
Soldering	Mildly activated rosin fluxes are preferred. JANTEK terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.	
Lead Free Solder re-flow:	Recommended temperature profiles for re-flow soldering in Figure 1.	
Soldering Iron:	<p>Products attachment with a soldering iron is discouraged due to the inherent process control limitations. If a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.</p> <p>Note :</p> <ul style="list-style-type: none"> <li>• Preheat circuit and products to 150°C</li> <li>• Never contact the ceramic with the iron tip</li> <li>• Use a 20 watt soldering iron with tip diameter of 1.0mm</li> <li>• 355°C tip temperature (max)</li> <li>• 1.0mm tip diameter (max)</li> <li>• Limit soldering time to 4~5 sec</li> </ul>	

Reflow Soldering



Reflow times: 3 times max  
Fig.1

Iron Soldering



Iron Soldering times : 1 times max  
Fig.2